IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under bot international and Pan-American copyright conventions.				nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information						
Supplie	r Information														
Company	name*	Company un	Company unique ID			Unique ID Authority					Response Date*				
onsemi												2023-06-08			
Contact N	Name	Title - Contact]	Phone - Contact*				Email - Contact*					
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Authorize	ed Representative*	Title - Representative]	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Dat	tive Date Version Manufacturing Site		ring Site	Weight*		UOM	Unit Type	
		FNA230	60	IPM SPM34 600V 30A			2023-06-08	23-06-08 CPA			4	9614.715	mg	Each	
Manufa	acturing Proccess Information	tion													
	Terminal Plating / Grid Array Material To		'erminal Base Alloy J-STD-020 M		-STD-020 MSI	L Rating	Peak Process Body Temperat		ture Max Time at Peak Temper		Temperatu	ire Numbe	r of Reflow Cy	eles	
	Matte Tin (Sn) - annealed		CU Alloy NA		NA		0 C		30 seco		secono	seconds 3			
Comments	S														
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated dipheny of an applicable quantity limit, please indicate fies that it gathered the information it provident. Supplier acknowledges that Company will we relied on information provided by others in the supplier agrees that, at a minimum and the Supplier enter into a written agreements ource of the Supplier's liability and the Com-	2011/65/EU and implemented by the laws of the End ethers (each a "RoHS restricted substance") in except the below which, if any, RoHS exemption you believe in this form using appropriate methods to ensure rely on this certification in determining the compliant completing this form, and that Supplier may not have its suppliers have provided certifications regarding ent with respect to the identified part, the terms and capany's remedies for issues that arise regarding information in the provided certification in	sess of the applicable quantity limit identified ab we may apply. If the part is an assembly with low its accuracy and that such information is true an- nce of its products with European Union member ave independently verified such information. Ho their contributions to the part, and those certification conditions of that agreement, including any warr	bove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. It is involved in situations where Supplier has not ations are at least as comprehensive as the ranty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	104.6 mg Supplier		Silicon (Si)	7440-21-3		104.6	mg	
Die Attach	195.0	mg	Supplier	Silver (Ag)	7440-22-4		5.85	mg
			Supplier	Tin (Sn)	7440-31-5		188.175	mg
			Supplier	Copper (Cu)	7440-50-8		0.975	mg
Die Attach Epoxy	1.85	mg	Supplier	Silver (Ag)	7440-22-4		1.702	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.148	mg
Die Attach Solder	1.7	mg	Supplier	Silver (Ag)	7440-22-4		0.0425	mg
			A	Lead (Pb)	7439-92-1	7a	1.5725	mg
			Supplier	Tin (Sn)	7440-31-5		0.085	mg
Heat Sink	6642.0	mg	Supplier	Aluminum (Al)	7429-90-5		6642	mg
Lead Frame	11022.5	mg	Supplier	Iron (Fe)	7439-89-6		16.5338	mg
			Supplier	Copper (Cu)	7440-50-8		11000.4551	mg
			Supplier	Phosphorus (P)	7723-14-0		5.5103	mg
Mold Compound-Black	31430.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		1571.5	mg
			Supplier	Carbon Black (C)	1333-86-4		314.3	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		27972.6992	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1571.5	mg
Plating	106.6	mg	Supplier	Tin (Sn)	7440-31-5		106.6	mg
Thermistor	10.0	mg	Supplier	Silver (Ag)	7440-22-4		0.8	mg
			Supplier	Tin (Sn)	7440-31-5		0.17	mg
			Supplier	Nickel Oxide (NiO)	1313-99-1		2.6	mg
			Supplier	Palladium (Pd)	7440-05-3		0.35	mg
			В	Nickel (Ni)	7440-02-0		0.08	mg
			Supplier	Cobalt Oxide (Co3O4)	1308-06-1		1.7	mg
			Supplier	Manganese Tetraoxide (Mn3O4)	1317-35-7		4.3	mg
Wire Bond - Al	100.0	mg	Supplier	Aluminum (Al)	7429-90-5		100	mg
Wire Bond - Cu	0.463	mg	Supplier	Palladium (Pd)	7440-05-3		0.0093	mg
			Supplier	Copper (Cu)	7440-50-8		0.4537	mg